

OVLGx0CyB9 Series

Features:

- Narrow beam angle
- High brightness LED
- Water clear plastic package
- UV resistant epoxy



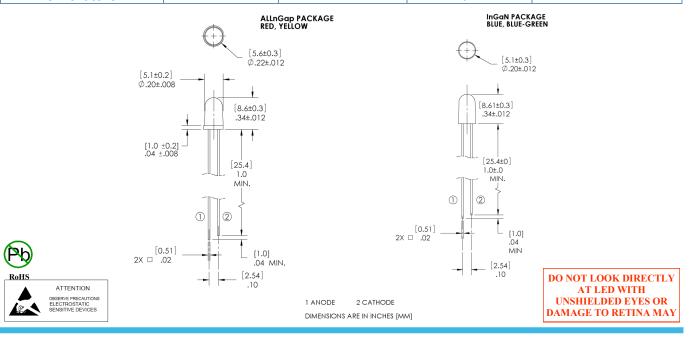
Description:

Each device in the **OVLG Series** is a high intensity LED mounted in a clear plastic T-1¾ package. Each device incorporates an integral molded lens that enables a narrow beam angle and provides an even emission pattern. Designed to produce light over a wide range of drive currents, these LEDs are useful in applications that require a higher on-axis brightness than that achievable with standard lamps.

Applications:

- Indoor/outdoor applications
- Variable message boards
- Store front signage

Part Number	Material	Emitted Color	Intensity Typ. mcd	Lens Color
OVLGB0C6B9	InGaN	Blue	7,200	
OVLGC0C6B9	IIIGan	Blue-Green	23,000	Clear
OVLGS0C8B9	AllaCaD	Red	14,000	Clear
OVLGY0C9B9	AlInGaP	Yellow	14,000	



General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.

TT Electronics | Optek Technology, Inc. 1645 Wallace Drive, Ste. 130, Carrollton, TX USA 75006 | Ph: +1 972 323 2200 www.ttelectronics.com | sensors@ttelectronics.com



OVLGx0CyB9 Series

Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Storage Temperature Range	-40 ~ +100 °C	
Operating Temperature Range	-40 ~ +100 °C	
Reverse Voltage		5 V
Continuous Farmand Comment	Blue, Blue-Green	25 mA
Continuous Forward Current	Red, Yellow	50 mA
Peak Forward Current (10% Duty Cycle, 1 kHz)	100 mA	
Dawey Dissipation	Blue, Blue-Green	100 mW
Power Dissipation	Red, Yellow	120 mW
Compatible and Auditory Andrian Towns	Blue, Blue-Green	-0.29 mA/° C
Current Linearity vs Ambient Temperature	Red, Yellow	-0.72 mA/° C
LED Junction Temperature	125° C	
Electrostatic Discharge Classification (JEDEC-JESD22-A114F)	Class 1C	
Lead Soldering Temperature (3 mm from the base of the epoxy bulb) ¹	260° C / 5 seconds	

Electrical Characteristics (T_A = 25°C unless otherwise noted)

SYMBOL	PARAMETER	COLOR	MIN	TYP	МАХ	UNITS	CONDITIONS	
l _V	Luminous Intensity	Blue	4,360	7,200		mcd		
		Blue-Green	11,970	23,000			I _F = 20 mA	
		Red	8,550	14,000				
		Yellow	8,550	14,000				
	Forward Voltage	Blue	2.6	3.2	4.0	- V	I _F = 20 mA	
V _F		Blue-Green						
		Red	1.0	2.0	2.4			
		Yellow	1.8					
	Reverse Current	Blue			10	μА	V _R = 5 V	
		Blue-Green						
I _R		Red						
		Yellow						
	Dominant Wavelength	Blue	460	470	475	nm	J. 204	
,		Blue-Green	499	505	511			
$\lambda_{\scriptscriptstyle D}$		Red	620	623	630		I _F = 20 mA	
		Yellow	585	589	595			
	50% Power Angle	Blue		15		- deg		
20½H-H		Blue-Green		15			1 20 1	
		Red		8			I _F = 20 mA	
		Yellow		8				

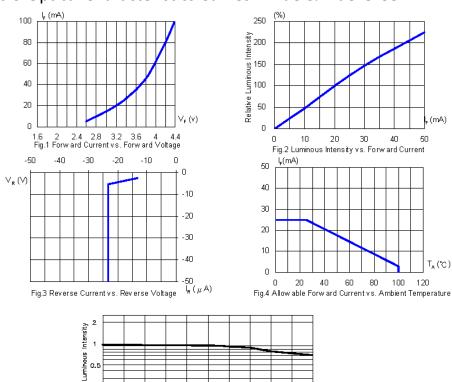
High-Intensity LED in Plastic T-1¾ Package

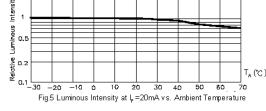


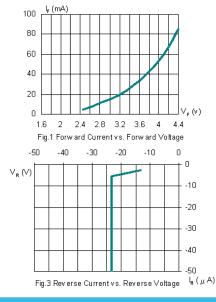
(mA)

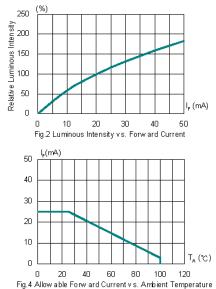
OVLGx0CyB9 Series

Typical Electro-Optical Characteristics Curves—Blue & Blue-Green





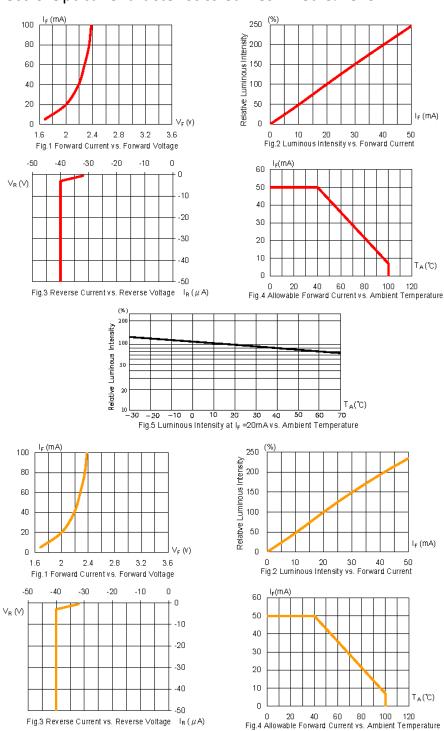






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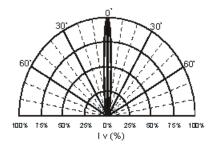
Typical Electro-Optical Characteristics Curves—Red & Yellow



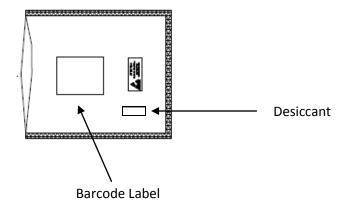


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Beam Angle:



Packaging: 500 pcs per anti-static bag with desiccant





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Reliability Test

LED lamps are checked by reliability tests based on MIL standards.

1. Test Conditions, Acceptable Criteria & Results

Classification	Test Item	Std. Test Method	Test Conditions	Duration	Unit	Acc / Rej Criteria	Result
Life Test	Operation Life Test (OLT)	MIL-STD-750D Method 1026.3	T _A =25°C , I _F =30mA *	1000 Hrs	100	0/1	Pass
Environmental Test	High Temperature Storage (HTS)	MIL-STD-750D Method 1032.1	T _A =100°C	1000 Hrs	100	0/1	Pass
	Low Temperature Storage (LTS)	MIL-STD-750D Method 1032.1	T _A =—40°C	1000 Hrs	100	0/1	Pass
	Temp. & Humidity with Bias (THB)	MIL-STD-750D Method 103B	T _A =85°C , Rh=85% I _F =20mA	500 Hrs	100	0/1	Pass
	Thermal Shock Test (TST)	MIL-STD-750D Method 1056.1	0°C ~ 100°C 2min 2min	100 cycles	100	0/1	Pass
	Temperature Cy- cling Test (TCT)	MIL-STD-750D Method 1051.5	-40°C ~ 25°C ~ 100°C ~ 25°C 30min 5min 30min 5min	100 cycles	100	0/1	Pass
Mechanical Test	Solderability	MIL-STD-750D Method 2026.4	235±5°C , 5 sec.	1 time	20	0/1	Pass
	Resistance to Sol- dering Heat	MIL-STD-750D Method 2031.1	260±5°C , 5 sec.	1 time	20	0/1	Pass
	Lead Integrity	MIL-STD-750D Method 2036.3	Load 2.5N (0.25kgf) 0°~90°~0°, bend	3 times	20	0/1	Pass

Remark: (*) $I_F = 30$ mA for AllnGaP chip; $I_F = 20$ mA for InGan chip (**) $I_F = 20$ mA for AllnGaP chip; $I_F = 10$ mA for InGan chip

2. Failure Criteria (T_A = 25°C):

Test Item	Symbol	Test Conditions	Criteria for Judgment		
			Min.	Max	
Luminous Intensity	I _V	I _F = 20mA	LSLx0.7 **		
Forward Voltage	V _F	I _F = 20mA		USLx1.1 *	

(*) USL: Upper Standard Level, (**) LSL: Lower Standard Level